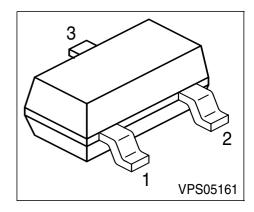


PNP Silicon Darlington Transistors

- High collector current
- High DC current gain



Туре	Marking	Pin Configuration Package			Package
SMBTA64	s2V	1 = B	2 = E	3 = C	SOT23

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	30	V
Collector-base voltage	V _{CBO}	30	
Emitter-base voltage	V _{EBO}	10	
DC collector current	l _C	500	mA
Peak collector current	/ _{CM}	800	Α
Base current	I _B	100	mA
Peak base current	/ _{BM}	200	
Total power dissipation, T_S = 81 °C	P _{tot}	330	mW
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	-65 150	

Thermal Resistance

Junction - soldering point ¹⁾	R _{thJS}	≤210	K/W

 $^{^{1}\}mbox{For calculation of}\,R_{\mbox{\scriptsize thJA}}$ please refer to Application Note Thermal Resistance



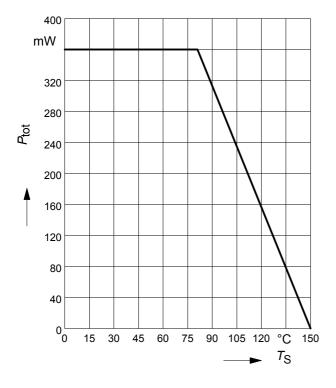
Electrical Characteristics at T_A = 25°C, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	1
DC Characteristics					•
Collector-emitter breakdown voltage	V _{(BR)CES}	30	-	-	V
$I_{\rm C} = 10 \ \mu \text{A}, \ V_{\rm BE} = 0$					
Collector-base breakdown voltage	$V_{(\mathrm{BR})\mathrm{CBO}}$	30	-	-	
$I_{\rm C} = 10 \ \mu \text{A}, \ I_{\rm E} = 0$					
Emitter-base breakdown voltage	$V_{(BR)EBO}$	10	-	-	
$I_{\rm E}$ = 10 μ A, $I_{\rm C}$ = 0					
Collector cutoff current	I _{CBO}	ı	-	100	nA
$V_{\rm CB} = 30 \text{ V}, I_{\rm E} = 0$					
Collector cutoff current	<i>I</i> _{CBO}	-	-	10	μA
$V_{\rm CB}$ = 30 V, $I_{\rm E}$ = 0 , $T_{\rm A}$ = 150 °C					
Emitter cutoff current	I _{EBO}	-	-	100	nA
$V_{\rm EB} = 10 \text{ V}, I_{\rm C} = 0$					
DC current gain 1)	h _{FE}				-
$I_{\rm C}$ = 10 mA, $V_{\rm CE}$ = 5 V		10000	-	-	
$I_{\rm C}$ = 100 mA, $V_{\rm CE}$ = 5 V		20000	-	-	
Collector-emitter saturation voltage1)	V _{CEsat}	-	-	1.5	V
$I_{\rm C}$ = 100 mA, $I_{\rm B}$ = 0.1 mA					
Base-emitter saturation voltage 1)	V_{BEsat}	-	-	2	
$I_{\rm C}$ = 100 mA, $I_{\rm B}$ = 0.1 mA					
AC Characteristics					
Transition frequency	f _T	125	-	-	MHz
$I_{\rm C}$ = 50 mA, $V_{\rm CE}$ = 5 V, f = 20 MHz					

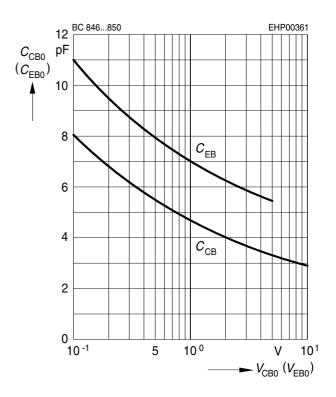
¹⁾ Pulse test: $t \le 300\mu s$, D = 2%



Total power dissipation $P_{tot} = f(T_S)$

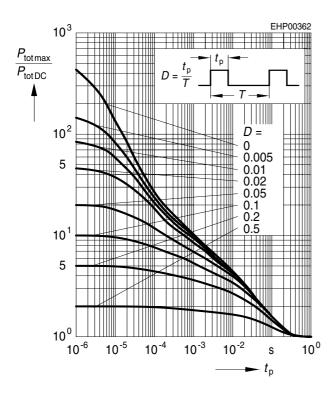


Collector-base capacitance $C_{CB} = f(V_{CBO})$ Emitter-base capacitance $C_{EB} = f(V_{EBO})$



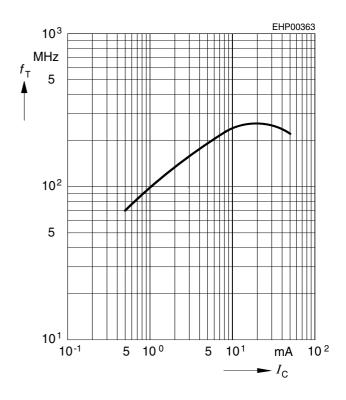
Permissible pulse load

$$P_{\text{totmax}} / P_{\text{totDC}} = f(t_{p})$$



Transition frequency $f_T = f(I_C)$

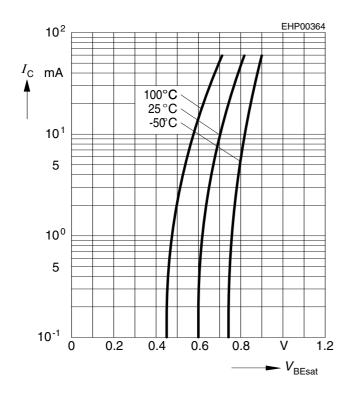
$$V_{CE} = 5V$$





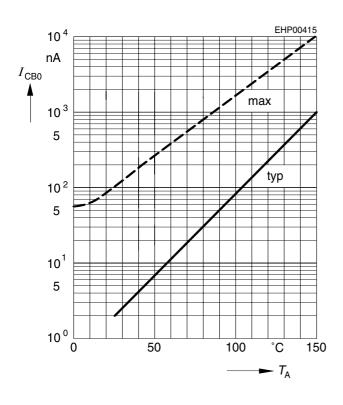
Base-emitter saturation voltage

$$I_{\rm C} = f(V_{\rm BEsat}), h_{\rm FE} = 20$$



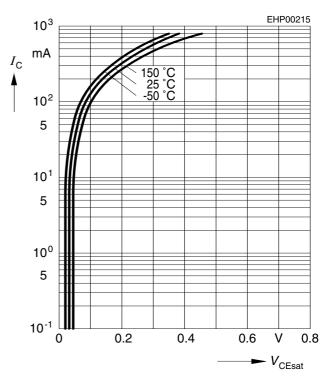
Collector cutoff current $I_{CBO} = f(T_A)$

$$V_{\text{CB}} = 30 \text{V}$$



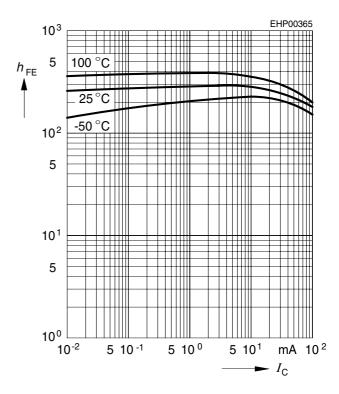
Collector-emitter saturation voltage

$$I_{\rm C} = f(V_{\rm CEsat}), h_{\rm FE} = 20$$



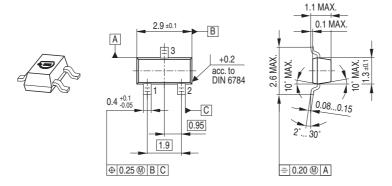
DC current gain $h_{FE} = f(I_C)$

$$V_{CE} = 5V$$

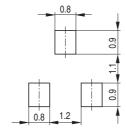




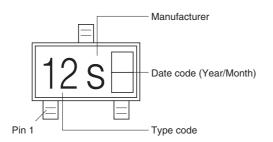
Package Outline

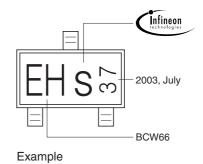


Foot Print



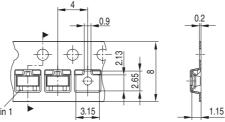
Marking Layout





Packing

Code E6327: Reel ø180 mm = 3.000 Pieces/Reel Code E6433: Reel ø330 mm = 10.000 Pieces/Reel





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